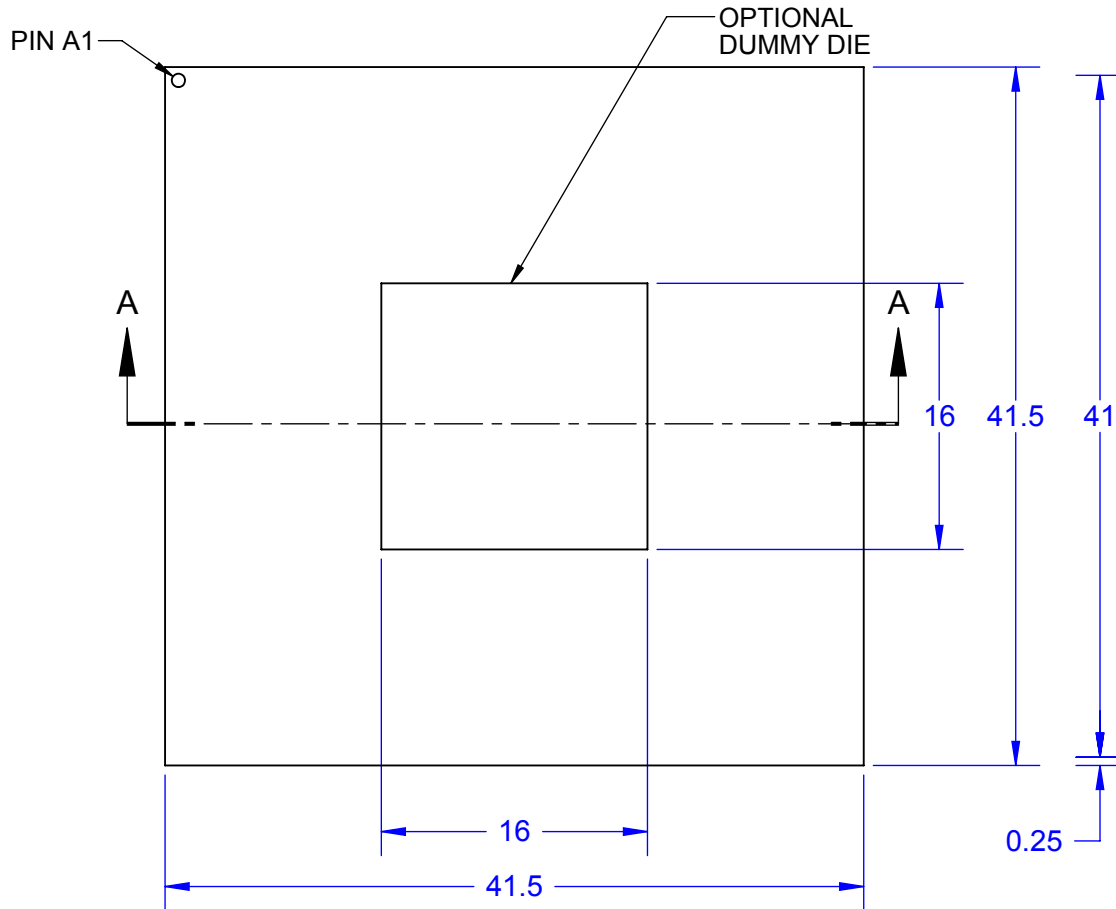
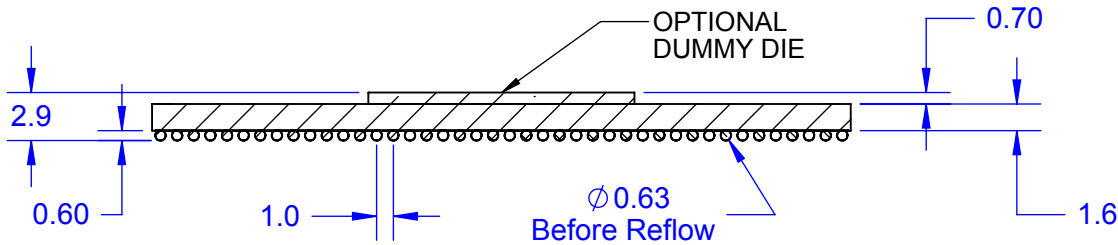
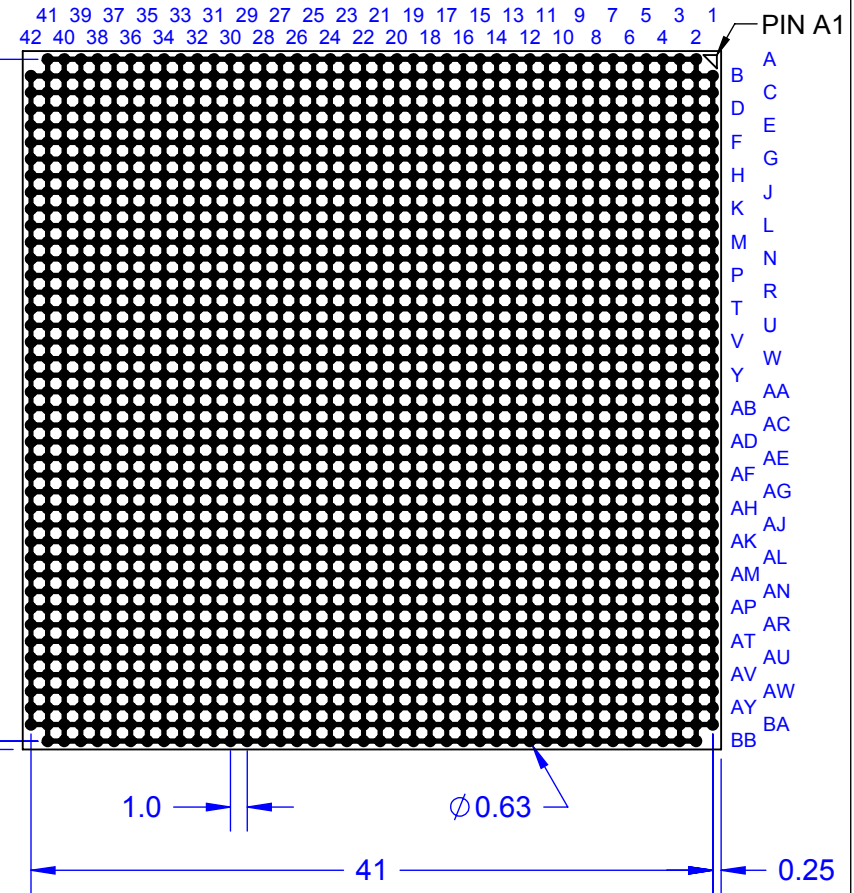


TOP VIEW



BALL VIEW




SECTION A-A

Notes: (Unless Otherwise Specified).

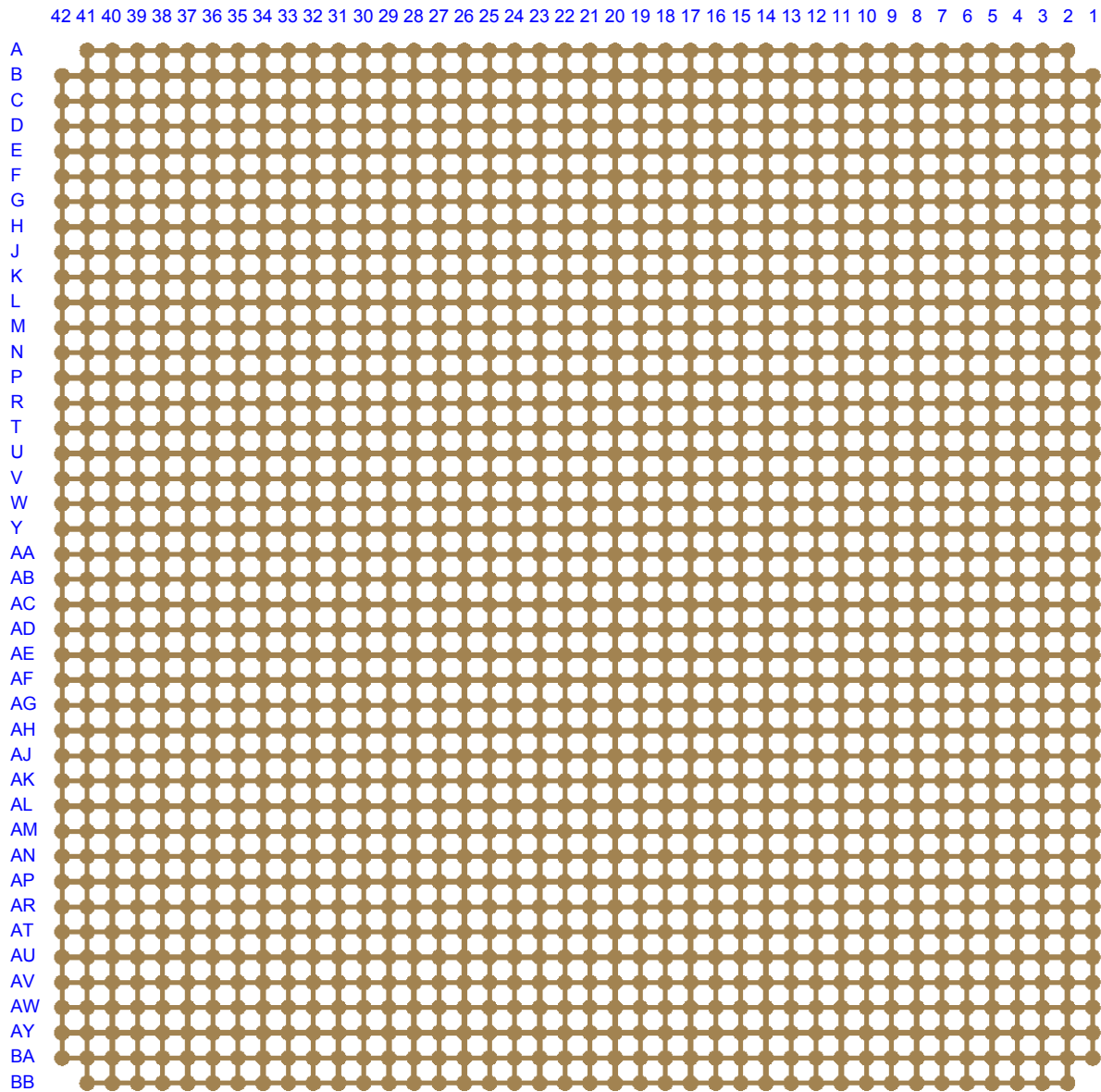
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.635mm (25 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.508mm (20 MIL).
- 5) PAD Cu DIAMETER: 0.685mm (27 MIL).
- 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

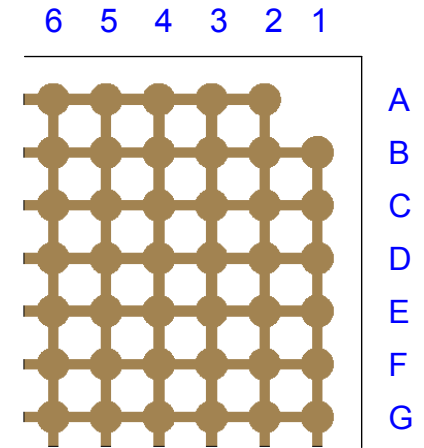
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
LBGA1760T1.0C-BUS	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA1760T1.0C-BUS-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA1760T1.0-BUS	Sn63/Pb37	NO	NO	NO
LBGA1760T1.0-BUS-D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE				
DRAWN T.Au	11/09/13				
ENG M. Hart	11/09/13	TITLE LBGA1760T1.0-BUS ALL PADS SHORTED			
MFG		SCALE 2.2:1	SIZE A	DRAWING NO. 514201	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 3
CUST					
REVISED					

BALL VIEW



DETAIL A



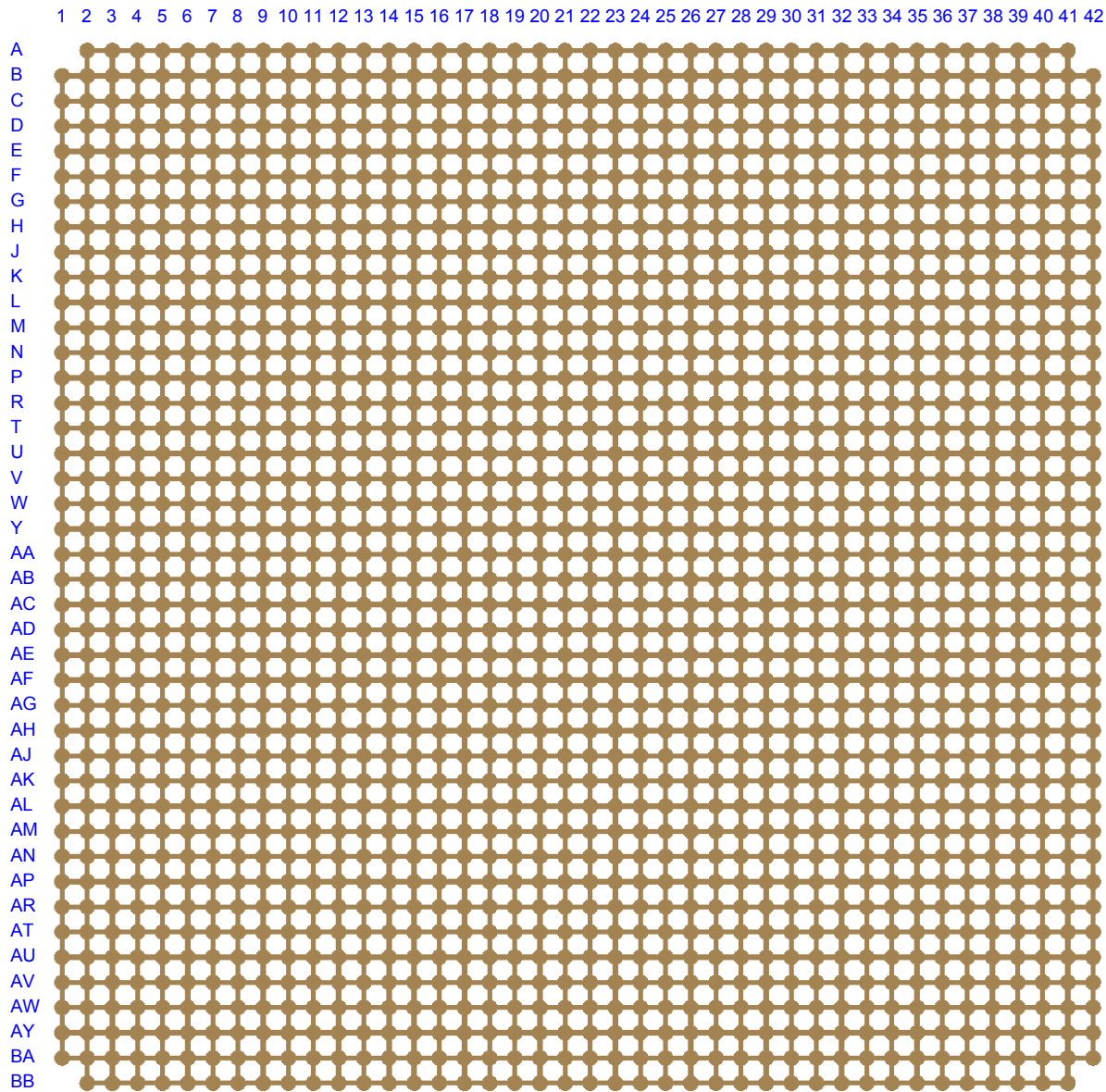
ALL BALLS
CONNECTED

Notes:

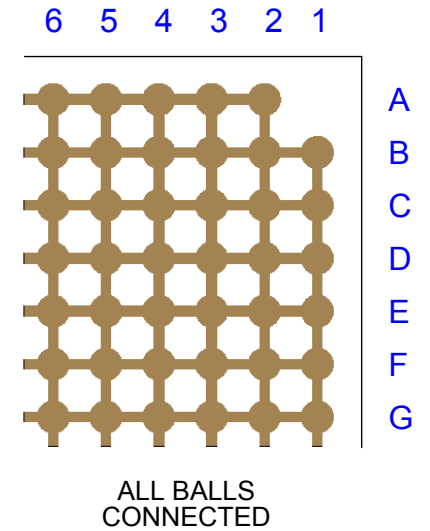
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.685mm (27 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.204mm (8 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.508mm (20 MIL).

TopLine®			
TITLE		LBGA1760T1.0-BUS ALL PADS SHORTED	
SCALE	SIZE	DRAWING NO.	REV
3.6:1	A	514201	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

BOTTOM SIDE (TOP X-RAY VIEW)



DETAIL B



TopLine®			
TITLE		LBGA1760T1.0-BUS ALL PADS SHORTED	
SCALE	SIZE	DRAWING NO.	REV
3.6:1	A	514201	A
DO NOT SCALE DRAWING			SHEET 3 OF 3